

# N-Channel Super Junction Power MOSFET $\,\,{\rm IV}$

#### **General Description**

The series of devices use advanced trench gate super junction technology and design to provide excellent R<sub>DS(ON)</sub> with low gate charge. This super junction MOSFET fits the industry's AC-DC SMPS requirements for PFC, AC/DC power conversion, and industrial power applications.

#### Features

- Optimized body diode reverse recovery performance
- •Low on-resistance and low conduction losses
- Small package
- ●Ultra Low Gate Charge cause lower driving requirements
- ●100% Avalanche Tested
- ROHS compliant

### Application

- Power factor correction (PFC)
- Switched mode power supplies(SMPS)
- Uninterruptible Power Supply (UPS)
- LLC Half-bridge

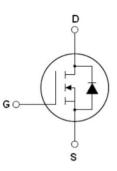
#### Package Marking And Ordering Information

Device	Device Package	Marking
NCE50NF130T	TO-247	NCE50NF130T

#### Table 1. Absolute Maximum Ratings (Tc=25℃)

Parameter	Symbol	Value	Unit
Drain-Source Voltage (VGs=0V)	VDS	500	V
Gate-Source Voltage (V <sub>DS</sub> =0V) ,AC (f>1 Hz)	Vgs	±30	V
Gate-Source Voltage (VDs=0V) ,DC	Vgs	±20	V
Continuous Drain Current at Tc=25°C	I <sub>D (DC)</sub>	23.5	A
Continuous Drain Current at Tc=100°C	I <sub>D (DC)</sub>	16.45	A
Pulsed drain current <sup>(Note 1)</sup>	DM (pluse)	70.5	A
Maximum Power Dissipation(Tc=25°C)	PD	186	W
Derate above 25°C		1.24	W/°C
Single pulse avalanche current (Note 2)	I <sub>AS</sub>	6	A
Reverse diode dv/dt, $V_{DS} \leqslant 400 \text{ V},I_{SD} < I_D$	dv/dt	15	V/ns
Drain Source voltage slope, $V_{DS} \leqslant 400 V$	dv/dt	50	V/ns
Operating Junction and Storage Temperature Range	TJ,TSTG	-55+175	°C

V <sub>DS min@Tjmax</sub>	550	V
Rds(on)typ.	110	mΩ
ID	23.5	A
Qg	24.5	nC



Schematic diagram

## ♦ Intrinsic fast-recovery body diode



TO-247



#### Table 2. Thermal Characteristic

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case (Maximum)	R <sub>thJC</sub>	0.80	°C /W
Thermal Resistance, Junction-to-Ambient (Maximum)	R <sub>thJA</sub>	62	°C /W

#### Table 3. Electrical Characteristics (TA=25°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit
On/off states						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V I <sub>D</sub> =250uA	500			V
Zero Gate Voltage Drain Current(Tc=25°C)	I <sub>DSS</sub>	V <sub>DS</sub> =500V,V <sub>GS</sub> =0V			10	μA
Zero Gate Voltage Drain Current(Tc=125°C)	I <sub>DSS</sub>	V <sub>DS</sub> =500V,V <sub>GS</sub> =0V			300	μA
Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±20V,V <sub>DS</sub> =0V			±200	nA
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> ,I <sub>D</sub> =250uA	3		5	V
Drain-Source On-State Resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =12A		110	130	mΩ
Dynamic Characteristics					· · ·	
Gate Resistance	Rg	F=1MHZ, D-S short		2		Ω
Input Capacitance	C <sub>lss</sub>			1544		pF
Output Capacitance	Coss	V <sub>DS</sub> =50V,V <sub>GS</sub> =0V, F=1MHz		630		pF
Reverse Transfer Capacitance	C <sub>rss</sub>			6.1		pF
Total Gate Charge	Qg			24.5		nC
Gate-Source Charge	Q <sub>gs</sub>	V <sub>DS</sub> =400V,I <sub>D</sub> =12A, V <sub>GS</sub> =10V		11.5		nC
Gate-Drain Charge	Q <sub>gd</sub>			6.5		nC
Gate plateau voltage	Vgp			7.7		V
Switching times						
Turn-on Delay Time	t <sub>d(on)</sub>			13		nS
Turn-on Rise Time	tr	V <sub>DD</sub> =400V,I <sub>D</sub> =12A,		10		nS
Turn-Off Delay Time	t <sub>d(off)</sub>	R <sub>G</sub> =4Ω,V <sub>GS</sub> =10V		58		nS
Turn-Off Fall Time	t <sub>f</sub>			9		nS
Source- Drain Diode Characteristics						
Source-drain current(Body Diode)	I <sub>SD</sub>	Tc=25°C			23.5	А
Pulsed-Source-drain current(Body Diode)	I <sub>SDM</sub>				70.5	А
Forward on voltage	V <sub>SD</sub>	Tj=25°C,I <sub>SD</sub> =23.5A,V <sub>GS</sub> =0V		0.9	1.1	V
Reverse Recovery Time	t <sub>rr</sub>	TL 0500 L 10		170		nS
Reverse Recovery Charge	Qrr	Тј=25°С,I⊧12д,		1.02		uC
Peak reverse recovery current	Irrm	di/dt=100A/µs		12		А

Notes: 1. Repetitive Rating: Pulse width limited by maximum junction temperature

2. Tj=25°C,VDD=50V,VG=10V, R\_G=25 $\Omega$ 



## **TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS (curves)**

#### Figure1. Safe operating area



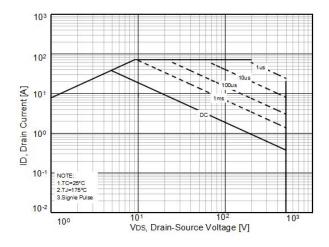


Figure3. Output characteristics

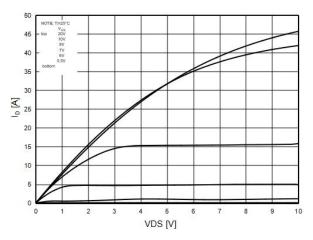
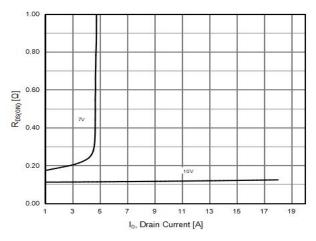


Figure 5. Static drain-source on resistance



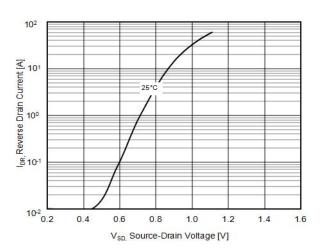


Figure4. Transfer characteristics

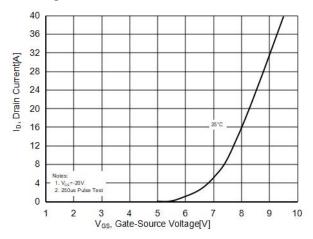
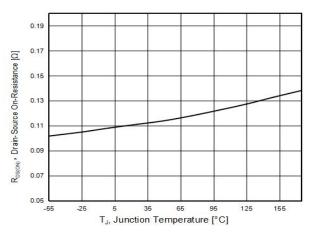


Figure6. R<sub>DS(ON)</sub> vs Junction Temperature





#### Figure7. BV<sub>DSS</sub> vs Junction Temperature

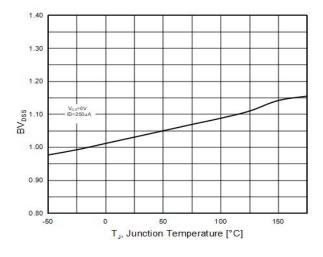


Figure9. Gate charge waveforms

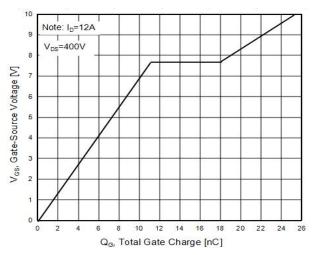
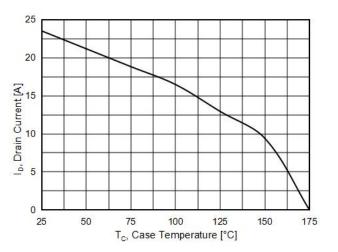
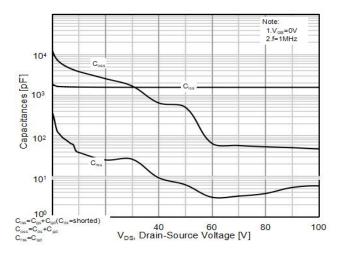


Figure8. Maximum I<sub>D</sub> vs Junction Temperature



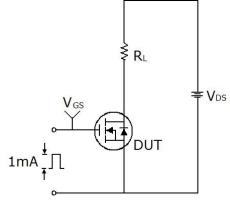


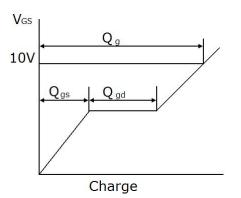




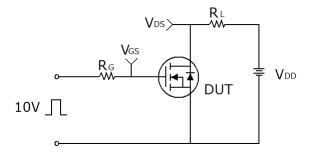
# **Test circuit**

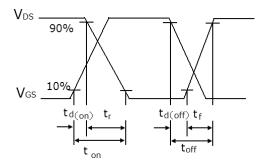
1) Gate charge test circuit & Waveform



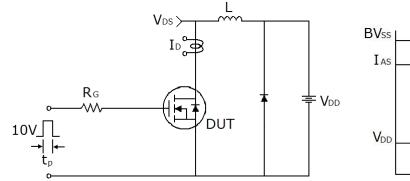


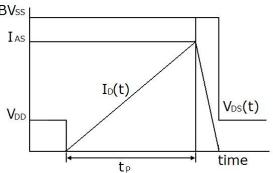
2) Switch Time Test Circuit:





#### 3) Unclamped Inductive Switching Test Circuit & Waveforms





02

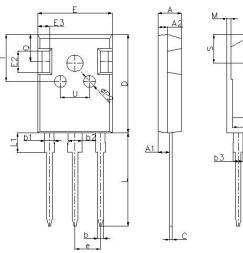
D1

E1

ась4



# **TO-247-E Package Information**



Currence al	Dimensions I	n Millimeters	Dimensions In Inches		
Symbol	Min.	Max.	Min.	Max.	
А	4.90	5.10	0.193	0.201	
A1	2.31	2.51	0.091	0.099	
A2	1.90	2.10	0.075	0.083	
b	1.16	1.26	0.046	0.050	
b1	1.96	2.06	0.077	0.081	
b2	2.96	3.06	0.117	0.120	
b3	-	2.25	-	0.089	
b4	-	3.25	-	0.128	
С	0.59	0.66	0.023	0.026	
D	20.90	21.10	0.823	0.831	
D1	16.25	16.85	0.640	0.663	
D2	1.05	1.35	0.041	0.053	
E	15.70	15.90	0.618	0.626	
E1	13.10	13.50	0.516	0.531	
E2	4.40	4.60	0.173	0.181	
E3	2.40	2.60	0.094	0.102	
е	5.436	5.436BSC		SC	
L	19.80	20.10	0.780	0.791	
L1	-	4.30	-	0.169	
М	0.35	0.95	0.014	0.037	
Р	3.40	3.60	0.134	0.142	
P1	7.00	7.40	0.276	0.291	
P2	2.40	2.60	0.094	0.102	
Q	5.60	6.00	0.220	0.236	
S	6.05	6.25	0.238	0.246	
Т	9.80	10.20	0.386	0.402	
U	6.00	6.40	0.236	0.252	



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